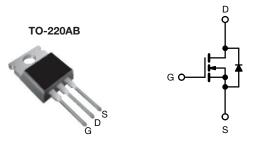
Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

## **E Series Power MOSFET**



N-Channel MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.104			
Q <sub>g</sub> max. (nC)	4	5			
Q <sub>gs</sub> (nC)	1	0			
Q <sub>gd</sub> (nC)	1	2			
Configuration	Sin	Single			

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) R<sub>on</sub> x Q<sub>g</sub>
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP120N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600		
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	25		
		T <sub>C</sub> = 100 °C		16	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	66		
Linear derating factor				1.4	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	88	mJ	
Maximum power dissipation			$P_{D}$	179	W	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	70	1//		
Reverse diode dv/dt <sup>d</sup>			50	- V/ns		
Soldering recommendations (peak temperature) <sup>c</sup>	For 10 s			260	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 2.5 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	1	40	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.7	C/VV	

SPECIFICATIONS (T <sub>J</sub> = 25 °C, t	ınless otherwi	se noted)					
PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.67	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Cata aguraa laakaga	,	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zara gata valtaga duain avurant	,	V <sub>DS</sub> =	= 600 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 480 \text{ V}$	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A	-	0.104	0.120	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 20 V, I <sub>D</sub> = 12 A	-	6	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	1562	-	-
Output capacitance	C <sub>oss</sub>	]	V <sub>DS</sub> = 100 V,	-	72	-	
Reverse transfer capacitance	C <sub>rss</sub>	1	f = 1 MHz		6	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	56	-	pF
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	357	-	
Total gate charge	Qg			-	30	45	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 12 \text{ A}, V_{DS} = 480 \text{ V}$	-	10	-	
Gate-drain charge	Q <sub>gd</sub>	1			12	-	]
Turn-on delay time	t <sub>d(on)</sub>		$V_{DD} = 480 \text{ V}, I_{D} = 12 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		19	38	- ns
Rise time	t <sub>r</sub>	V <sub>DD</sub> =			65	130	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =			31	62	
Fall time	t <sub>f</sub>			-	33	66	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.3	0.65	1.3	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	25	
Pulsed diode forward current	I <sub>SM</sub>			-	-	66	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 12 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 12 \text{A},$ $di/dt = 100 \text{A/µs}, V_R = 400 \text{V}$		-	322	870	ns
Reverse recovery charge	Q <sub>rr</sub>			-	4.9	18.4	μC
Reverse recovery current	I <sub>RRM</sub>			-	29	-	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

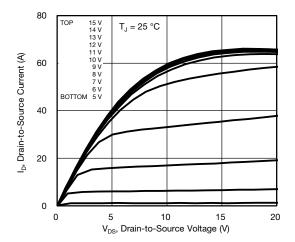


Fig. 1 - Typical Output Characteristics

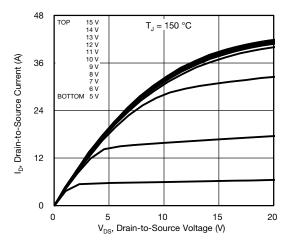


Fig. 2 - Typical Output Characteristics

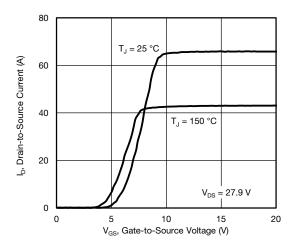


Fig. 3 - Typical Transfer Characteristics

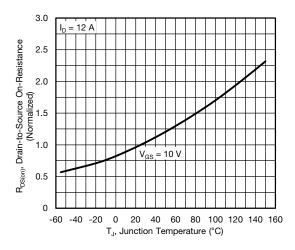


Fig. 4 - Normalized On-Resistance vs. Temperature

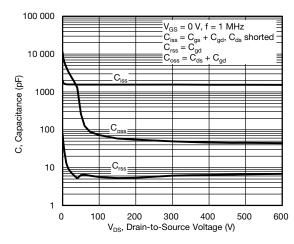


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

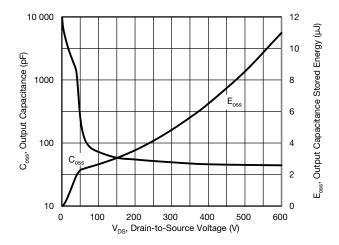


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



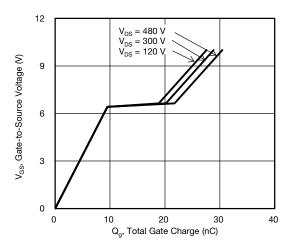


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

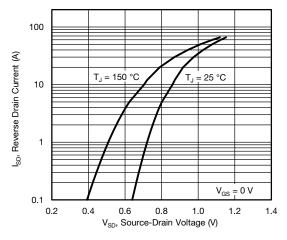


Fig. 8 - Typical Source-Drain Diode Forward Voltage

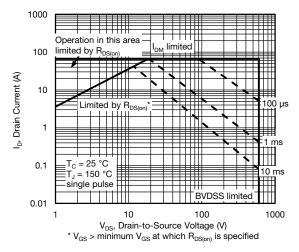


Fig. 9 - Maximum Safe Operating Area

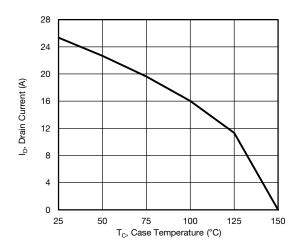


Fig. 10 - Maximum Drain Current vs. Case Temperature

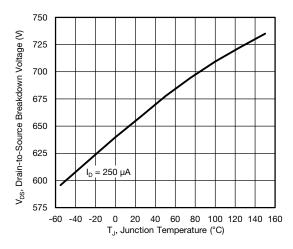


Fig. 11 - Temperature vs. Drain-to-Source Voltage



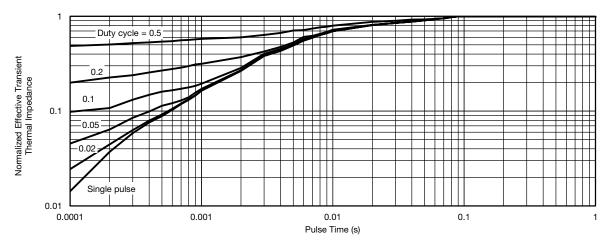


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

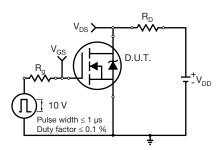


Fig. 13 - Switching Time Test Circuit

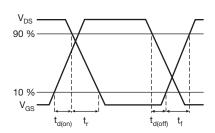


Fig. 14 - Switching Time Waveforms

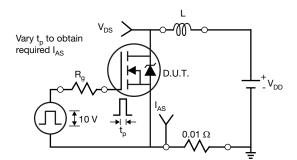


Fig. 15 - Unclamped Inductive Test Circuit

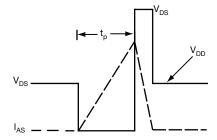


Fig. 16 - Unclamped Inductive Waveforms

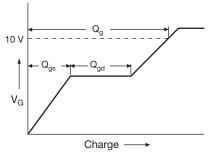


Fig. 17 - Basic Gate Charge Waveform

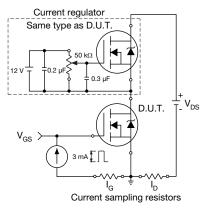


Fig. 18 - Gate Charge Test Circuit

S18-0932-Rev. A, 17-Sep-2018



#### Peak Diode Recovery dv/dt Test Circuit

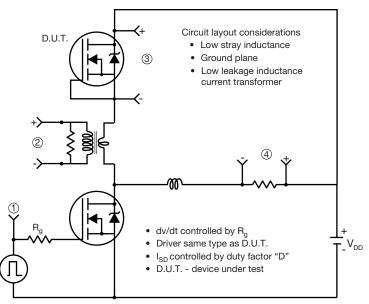




Fig. 19 - For N-Channel

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